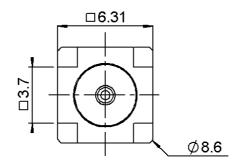
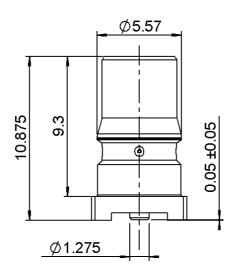
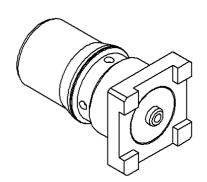
**REEL 100** 

R123.427.803

Series : **QMA** 











All dimensions are in mm.

		4
 	,	

COMPONENTS	MATERIALS	PLATING (µm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS	BRASS BERYLLIUM COPPER - PTFE	NPGR NPGR -
-	-	-

**Issue:** 0923 D

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



**REEL 100** 

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Series: QMA

## **PACKAGING**

Standard	Unit	Other
100	'W' option	Contact us

## **SPECIFICATION**

## **ELECTRICAL CHARACTERISTICS**

 $\begin{array}{ccc} \text{Impedance} & & \textbf{50} \;\; \Omega \\ \text{Frequency} & & \textbf{0-6} \;\; \text{GHz} \end{array}$ 

VSWR 1.04 + 0,0450 x F(GHz) Maxi

Insertion loss  $0.05 \ \sqrt{F(GHz)} \ Maxi$ 

RF leakage - ( **80** - F(GHz)) dB Maxi Voltage rating **500** Veff Maxi

Voltage rating 500 Veff Maxi Dielectric withstanding voltage Insulation resistance 5000 M $\Omega$  mini

## **ENVIRONMENTAL**

Operating temperature -40/+105 ° C

Hermetic seal NA Atm.cm3/s

Panel leakage NA

## **OTHER CHARACTERISTICS**

Assembly instruction NA

Others:

## **MECHANICAL CHARACTERISTICS**

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

27 N mini
27 N mini
28 N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 100 Cycles mini

Weight **1,2180** g

Intermod.:-120dBc at 1.8GHz(2 x 20W) RF leakage:Interf. only:3<F<6GHz:>70dB

**Issue:** 0923 D

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RADIALL

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## **SMT RECEPTACLE**

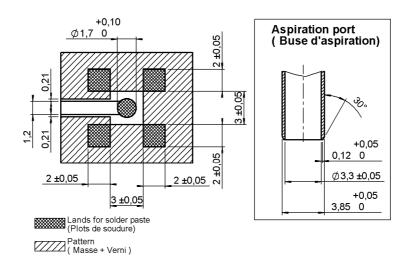
Series: QMA

# **REEL 100**

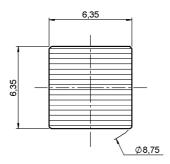
#### **QMA SERIE - INFORMATIONS**

COPLANAR LINE: Pattern and signal are on the same side. Thickness of PCB = 0.063 (1.6mm).

The material of PCB is the epoxy resin of glass fabrics bacs (Er = 4.8). The solder resist should be printed except for the land pattern on the PCB.



## SHADOW OF QUICLOCK RECEPTACLE FOR VIDEO CAMERA



**Issue:** 0923 D

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



**REEL 100** 

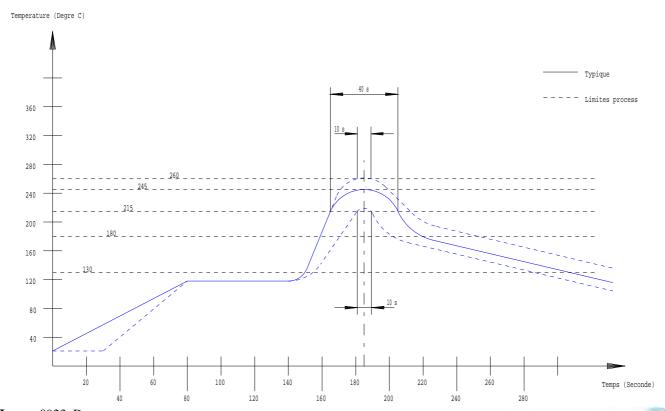
# R123.427.803

Series: QMA

## **SOLDER PROCEDURE**

- 1. Deposit solder paste 'SN62RP11AGS90' on mounting zone by screen printing application. We recommend a low residue flux.
  - We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
- Placement of the receptacle on the mounting zone with an automatic 'pick and place' machine.
   Video camera is preferred to check the positioning of the component (See page 3).
   Adhesive agents are forbidden on the receptacle.
- Soldering by infra-red reflow.
   We give under, the typical profile to use.
- 4. Cleaning of the printed circuits board.
- 5. Checking of solder joints and position of the components by visual inspection.

# TEMPERATURE PROFIL



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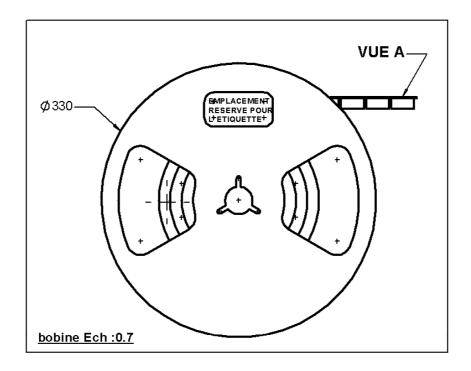
In the effort to improve our products, we reserve the right to make changes judged to be necessary.

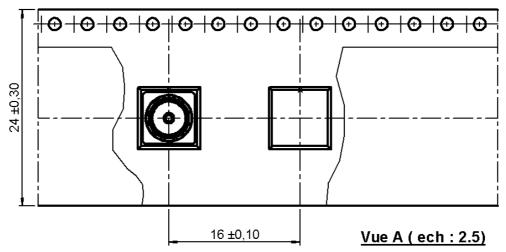


**REEL 100** 

R123.427.803

Series : **QMA** 





**Issue:** 0923 D

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